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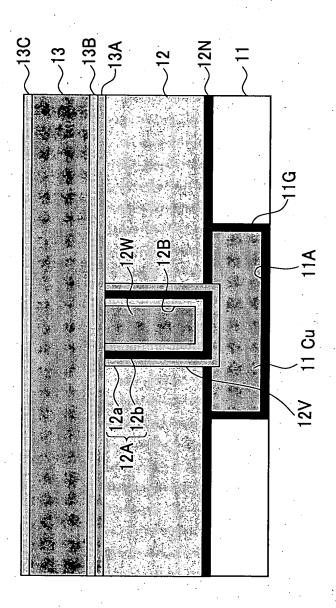
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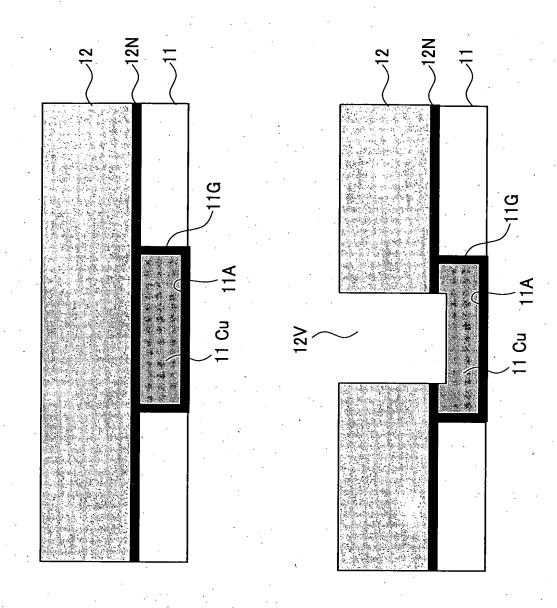


FIG.2A

FIG.2B

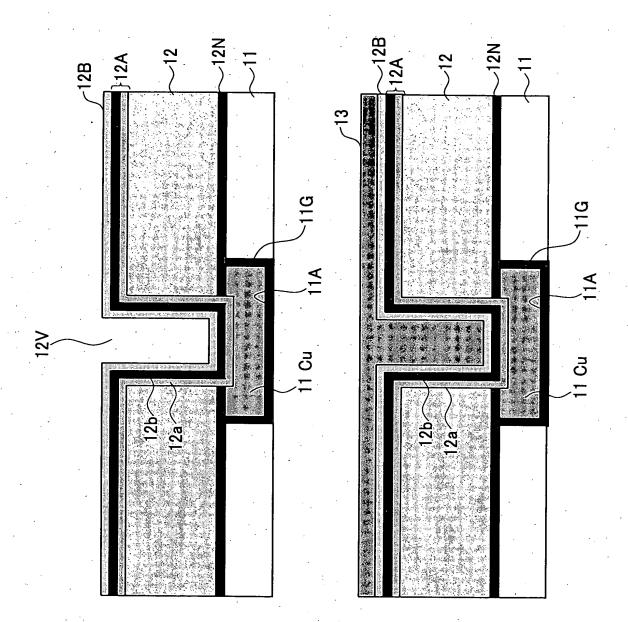
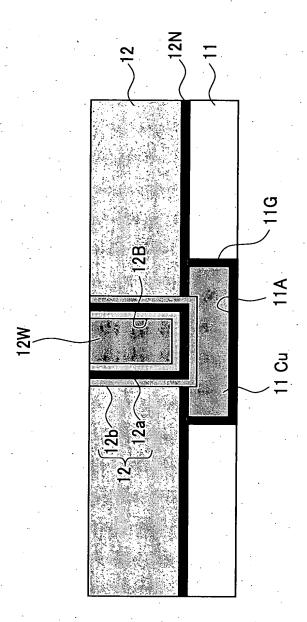


FIG. 20

FIG.2D



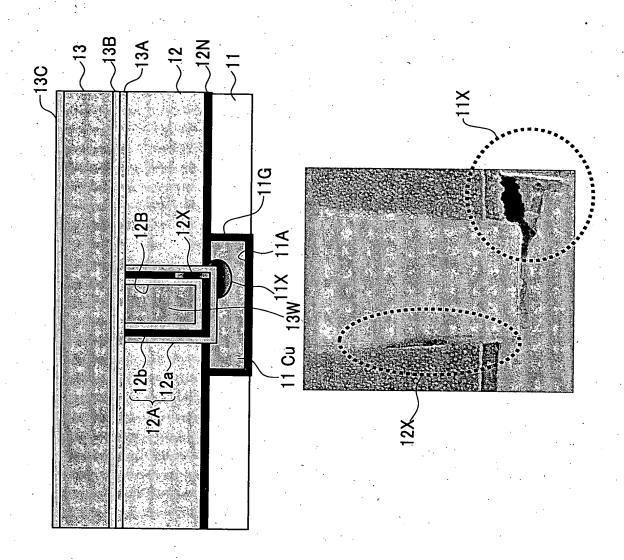
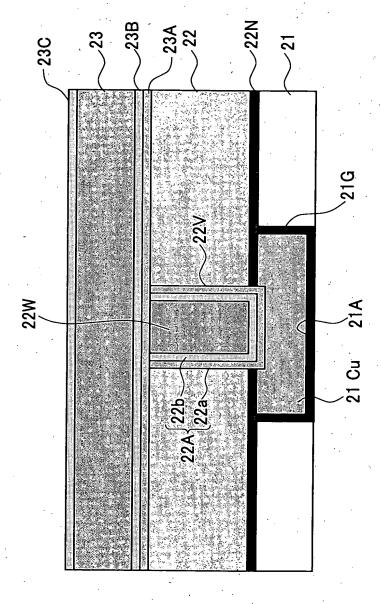
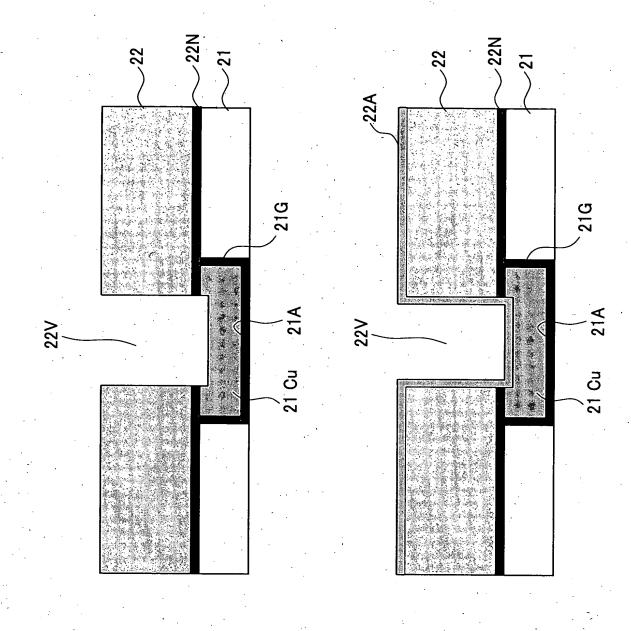


FIG.3A

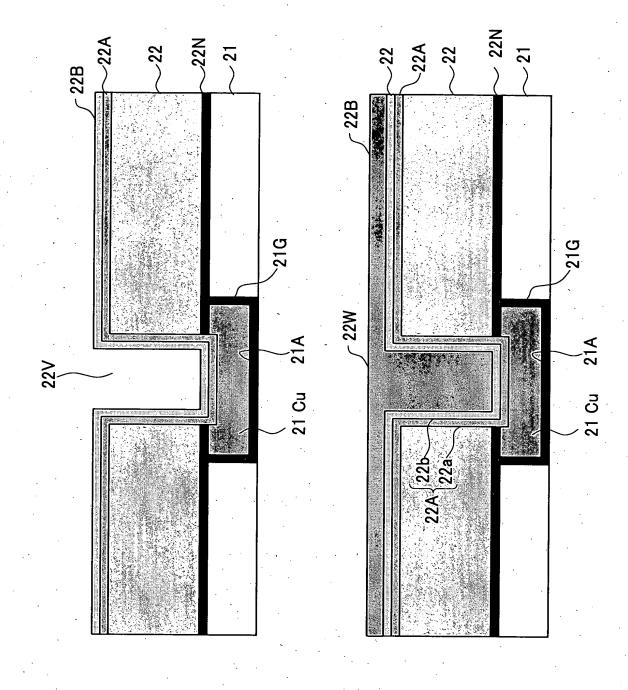
FIG.3B





-IG.5A

-IG.5B

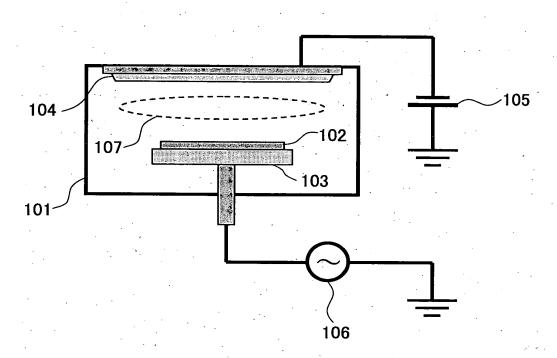


**FIG.5C** 

FIG.5D

FIG.6

<u>100</u>



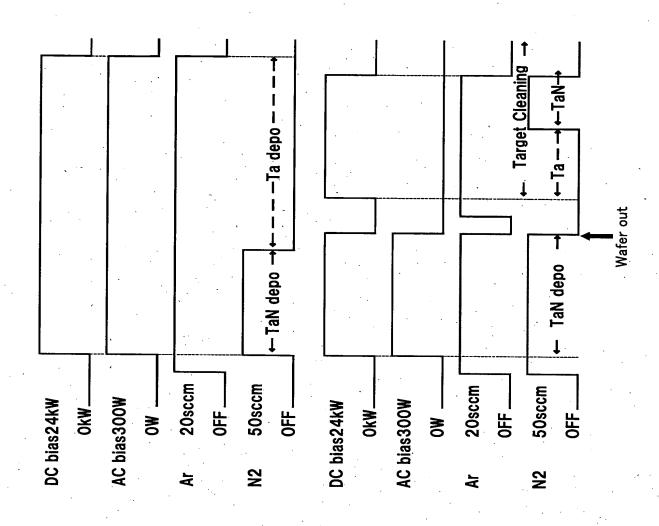


FIG.8

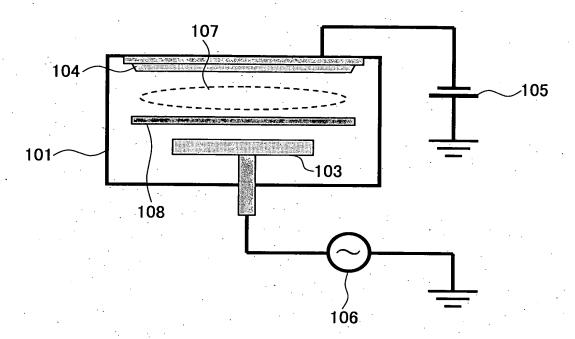
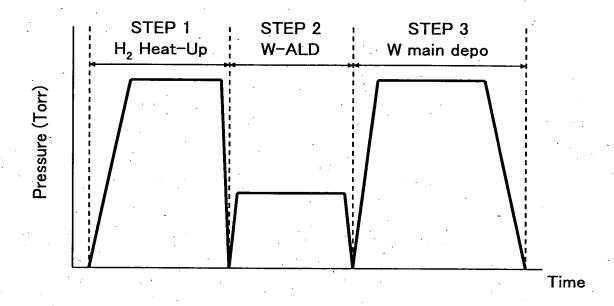
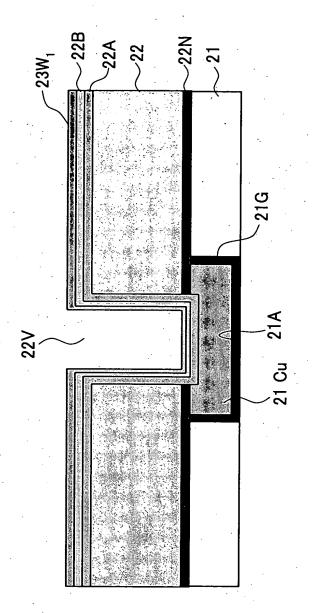


FIG.9





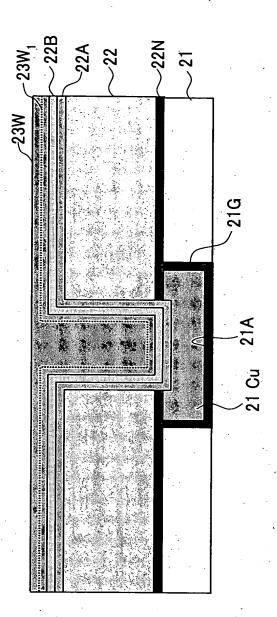
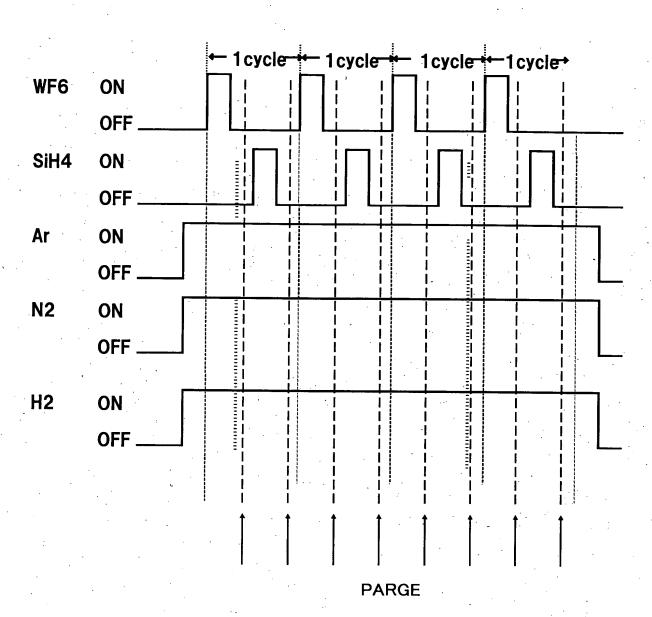


FIG. 10A

FIG. 10B

FIG.11



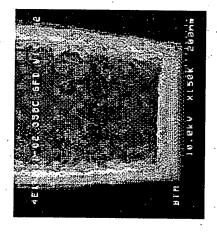
Title: SEMICONDUCTOR DEVICE HAVING A MULTILAYER INTERCONNECTION ... By: Toshio TAKAYAMA, et al. Docket No.: 031325

46180 # 02; 330C SFD # HE

BIN 18. BK X156F 265mm

FIG. 12E

FIG.12D



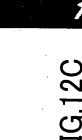
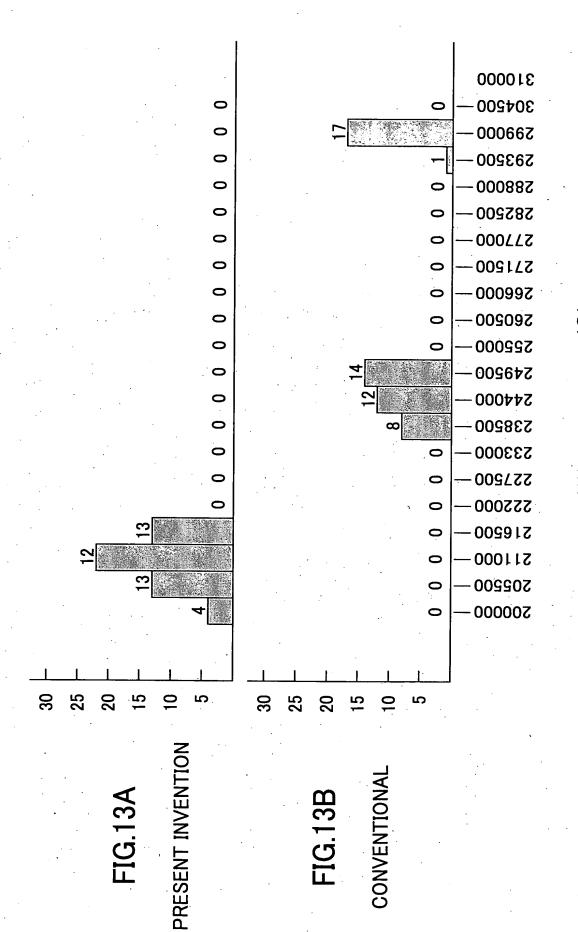
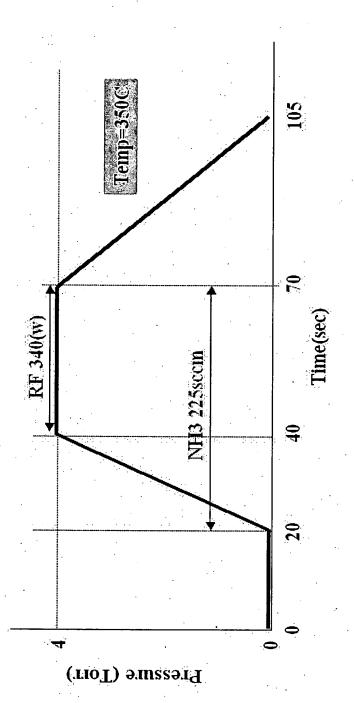
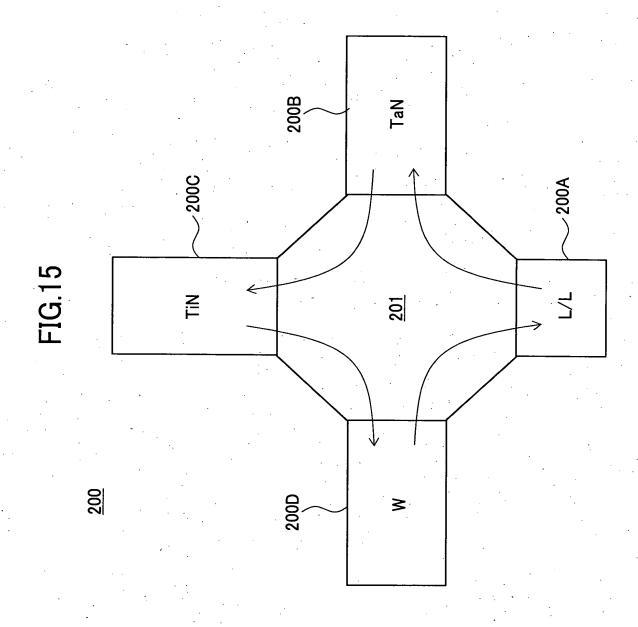


FIG. 12A



CHAIN RESISTANCE (요)





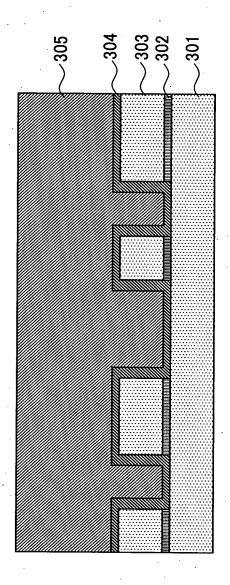


FIG.16A

FIG.16B

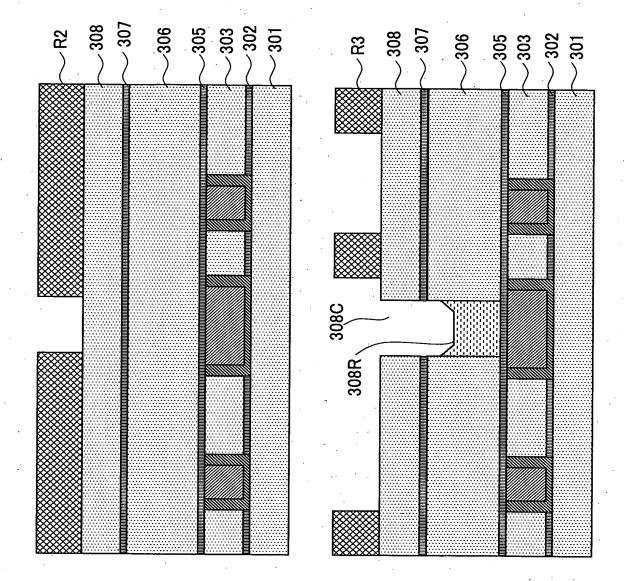
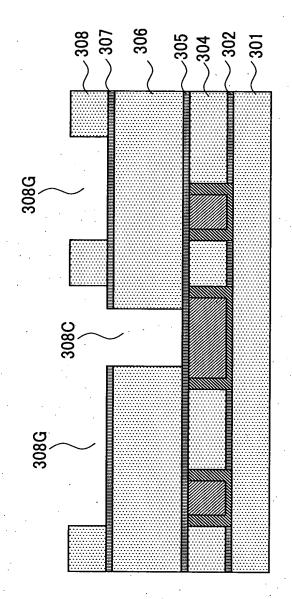


FIG.16D



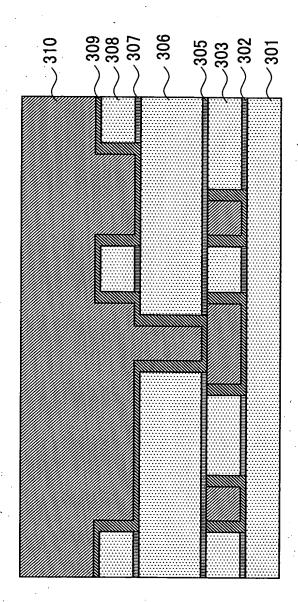
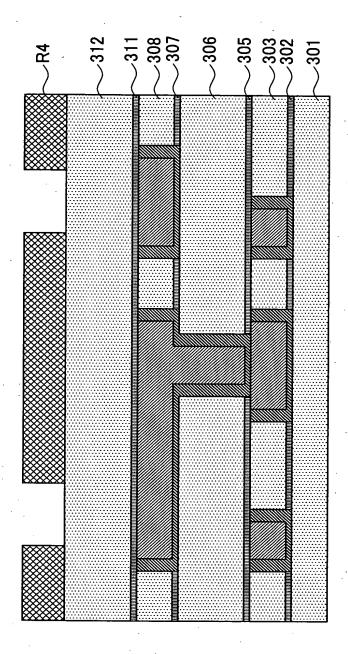


FIG.16E

FIG. 16F



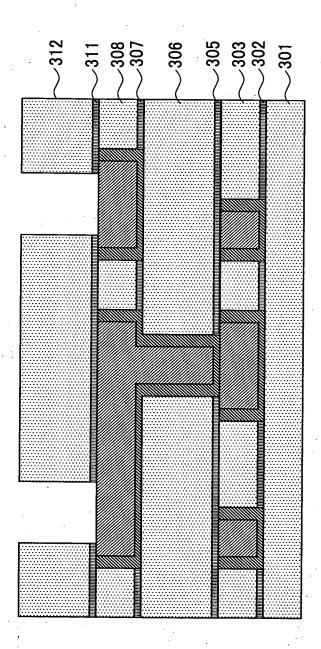


FIG. 16H

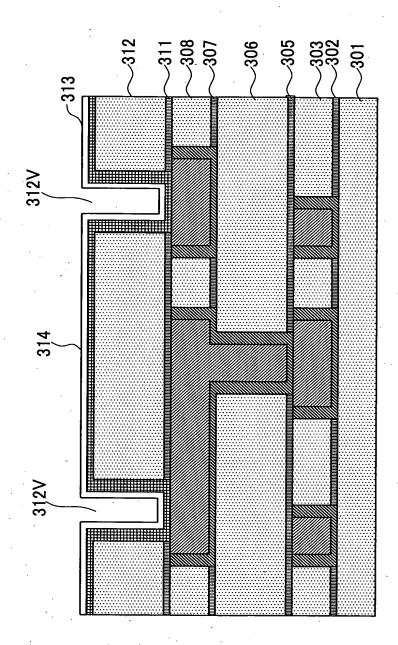
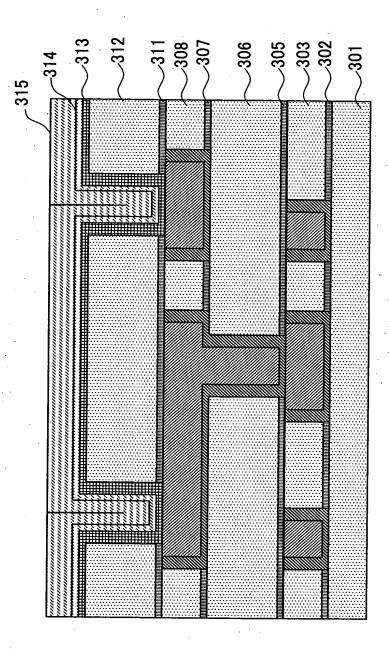
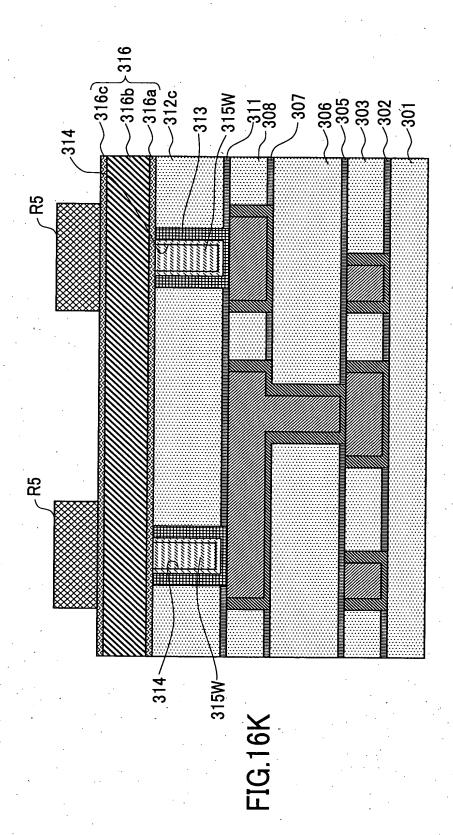


FIG. 161



-IG.16J



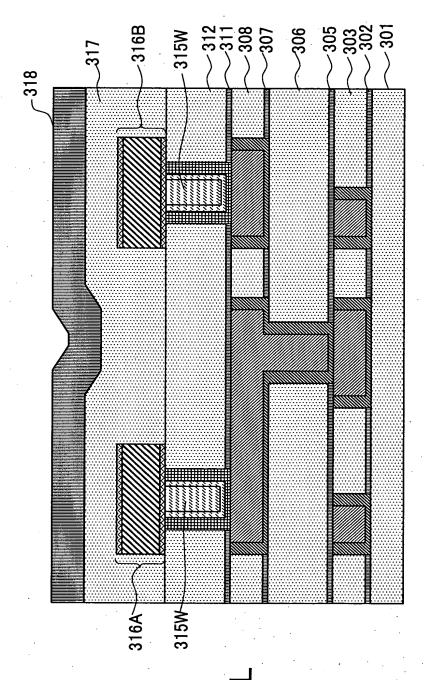


FIG. 161

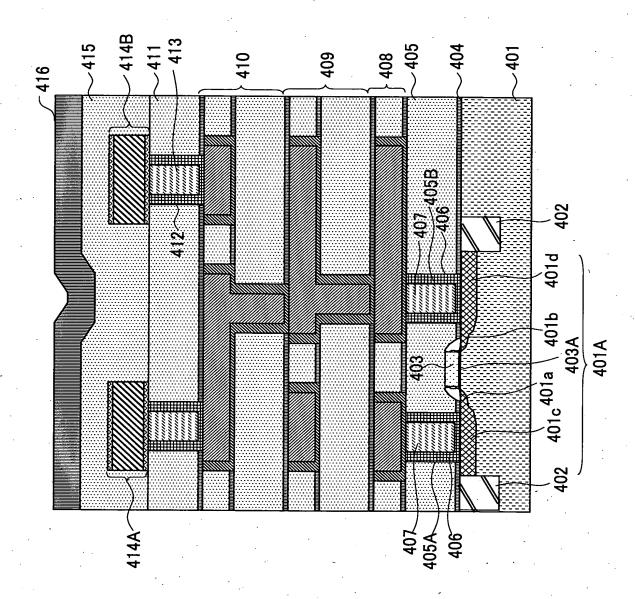


FIG. 17